



## Product Change Notification - RMES-31VQKE033

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**Date:**

10 Jun 2019

**Product Category:**

Depletion Mode MOSFETs; Linear Regulator ICs

**Affected CPNs:****Notification subject:**

CCB 3458 Final Notice: Qualification of GTBF as a new assembly site for selected products available in 3L TO-220 package using 277 x 221 mils paddle size.

**Notification text:****PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

**NOTE:** For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**

Qualification of GTBF as a new assembly site for selected products available in 3L TO-220 package using 277 x 221 mils paddle size.

**Pre Change:**

Assembled at CARSEM using 2815A die attach, HCL-12S lead frame with 240 x 180 mils paddle size and CEL9240HF-10CM molding compound material

**Post Change:**

Assembled at GTBF using CRM-1800 die attach, LY80 lead frame with 277 x 221 mils paddle size and EME-G600 molding compound material

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	Carsem (M) SDN BHD (CARM)	Great Team Backend Foundry (Dong Guan) Ltd. (GTBF)
Wire material	Au wire	Au wire
Die attach material	2815A	CRM-1800
Molding compound material	CEL9240HF-10CM	EME-G600
Lead frame material	HCL-12S	LY80
Lead frame paddle size	240 x 180 mils	277 x 221 mils

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve on-time delivery performance by qualifying GTBF as a new assembly site using 277 x 221 mils paddle size. CARM assembly site will no longer have manufacturing support for 3L TO-220 package.



**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

July 10, 2019 (date code: 1928)

**Time Table Summary:**

	August 2018					>	June 2019					July 2019				
Workweek	31	32	33	34	35		22	23	24	25	26	27	28	29	30	31
Initial PCN Issue Date		X														
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date													X			

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**

**August 09, 2018:** Issued initial notification.

**May 22, 2019:** Re-issued initial notification. Added Lead frame paddle size information in notification subject, description of change and Pre and Post change summary table. Updated qualification plan to change the qual vehicle.

**June 10, 2019:** Issued final notification. Attached the qualification report and added estimated first ship date to July 10, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_RMES-31VQKE033\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

CL6N5-G

DN2535N5-G

DN2540N5-G